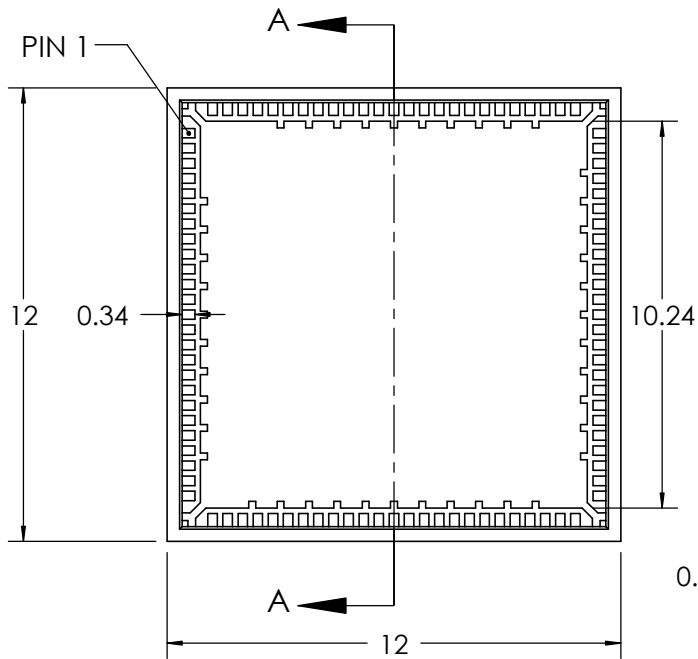
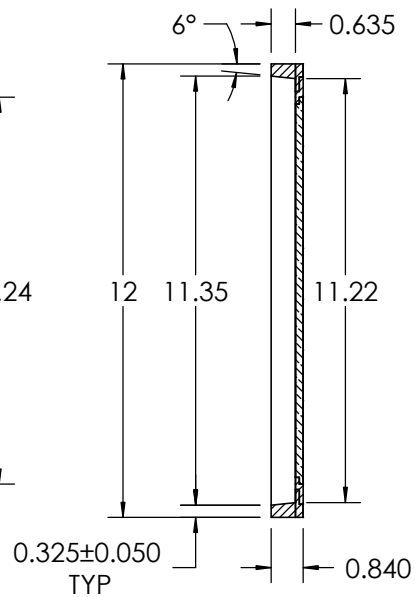


TOP VIEW

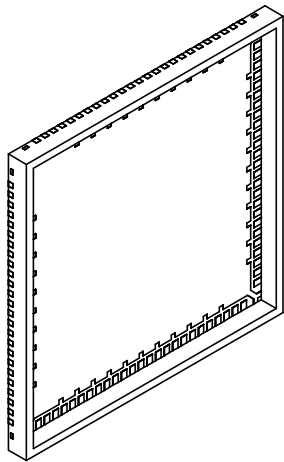
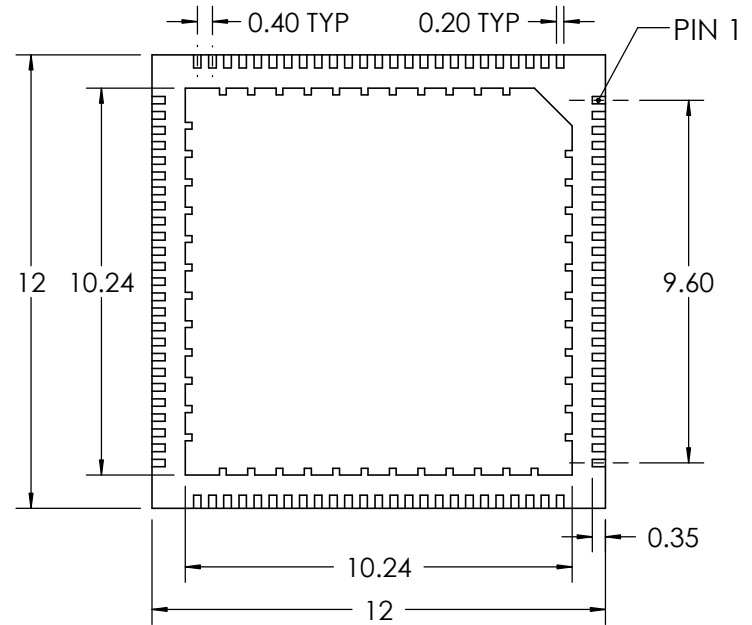


SIDE VIEW

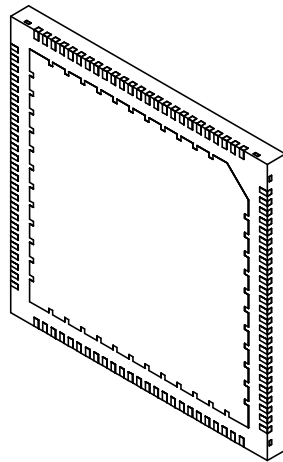


SECTION A-A

BOTTOM VIEW


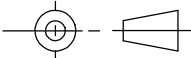


ISOMETRIC VIEW OF
CAVITY SIDE

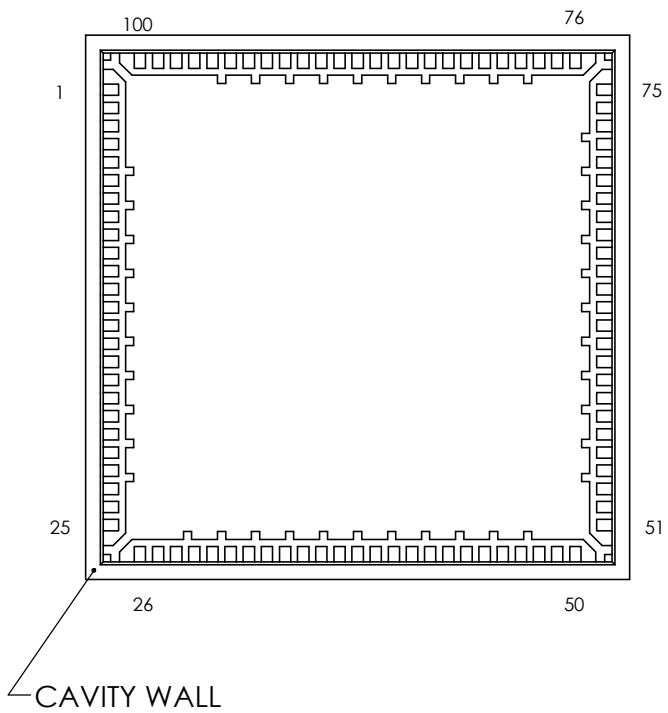


ISOMETRIC VIEW OF
PCB SIDE

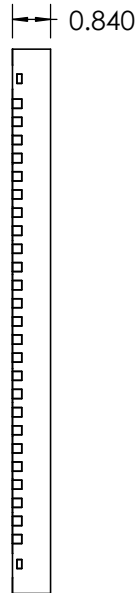
- Notes: (Unless Otherwise Specified)
- 1) BODY; PLASTIC, SEMICONDUCTOR GRADE
 - 2) LEAD FRAME: COPPER, C-194F/H
 - 3) LEAD FRAME PLATING: Ni, Pd, Au
 - 4) FRAME THICKNESS: 0.203mm
 - 5) DIE PAD: 10.24 X 10.24mm
 - 6) JEDEC OUTLINE: MO-220

TOLERANCES UNLESS NOTED		APPROVALS		DATE	 www.MirrorSemi.com
X.X	± 0.05	DRAWN	EDK	01/09/13	
X.XX	± 0.01	CHECKED			TITLE: 100-LEAD 12mm P=0.40mm QFN CAVITY PACKAGE
X.XXX	± 0.005	ENG APPR.			
X.XXXX	± 0.0005	MFG APPR.			
ALL DIMENSIONS IN		Q.A.			SCALE SIZE DWG. NO. REV 5:1 A 449970 A M-QFN100W.4
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		CUST.			
THIRD ANGLE PROJECTION 		REVISED			DO NOT SCALE DRAWING SHEET 1 OF 4

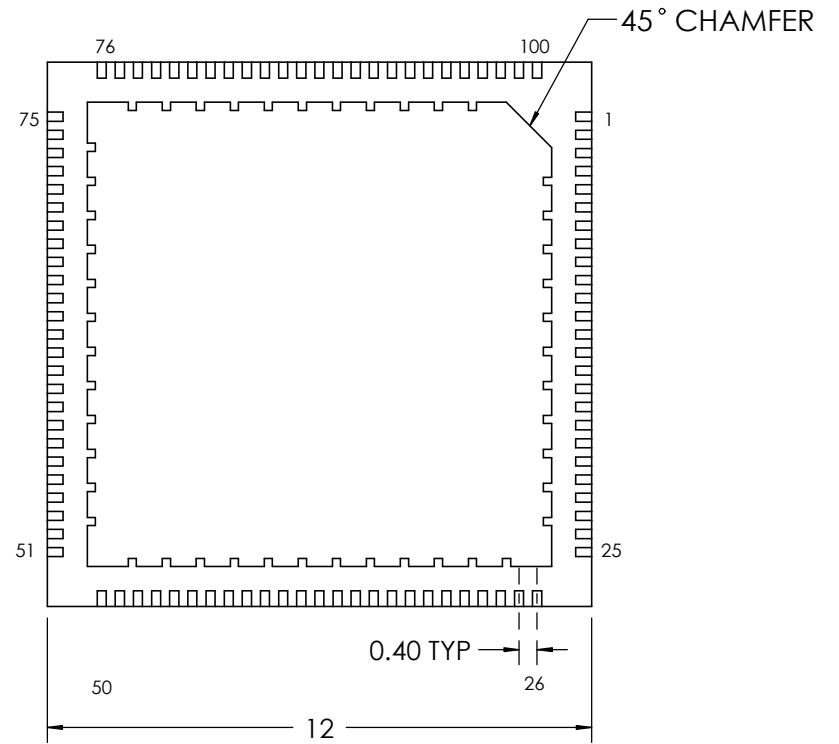
TOP VIEW



SIDE VIEW
(BEFORE LID ATTACH)



BOTTOM VIEW



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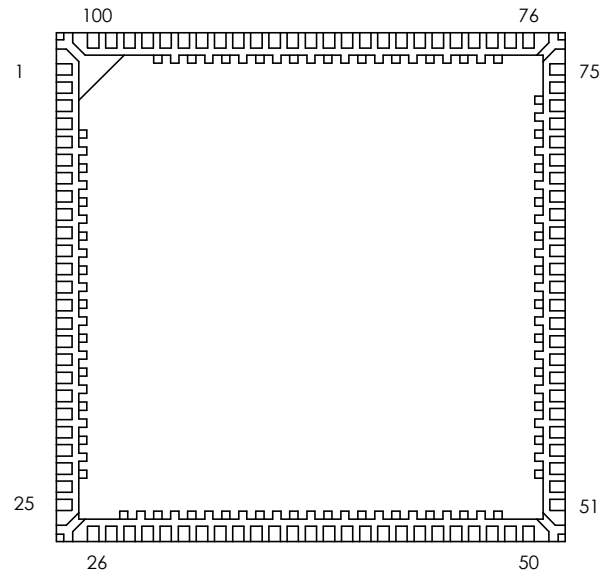
www.MirrorSemi.com

TITLE: 100-LEAD 12mm
P=0.40mm QFN CAVITY
PACKAGE
LEAD NUMBERING

SCALE	SIZE	DWG. NO.	REV
6:1	A	44970 M-QFN100W.4	A

DO NOT SCALE DRAWING SHEET 2 OF 4

BOND DIAGRAM



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Semiconductor™

www.MirrorSemi.com

TITLE: 100-LEAD 12mm
P=0.40mm QFN CAVITY
PACKAGE
BOND DIAGRAM

SCALE
6:1

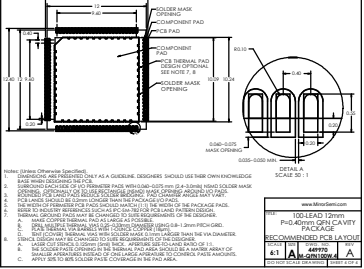
SIZE
A

DWG. NO.
449970
M-QFN100W.4

REV
A

DO NOT SCALE DRAWING

SHEET 3 OF 4



- Notes: (Refer to Package Description)
1. DIMENSIONS ARE METRIC; DIM. IN PARENTHESIS SHOWS U.S. DIMENSION. DIMENSIONS INCLUDE MET. TOLERANCES UNLESS OTHERWISE SPECIFIED.
 2. LEAD MOULDING COMPOUND SHALL BE A DUBBLEB, DUBBLEC, DUBBLEE OR DUBBLEF TYPE MOLDING COMPOUND.
 3. DIMENSIONS ARE TO CENTER UNLESS OTHERWISE SPECIFIED.
 4. DIMENSIONS FOR TRENCHES ARE TO CENTER UNLESS OTHERWISE SPECIFIED.
 5. DIMENSIONS OF THIS DRAWING ARE TO CENTER UNLESS OTHERWISE SPECIFIED.
 6. DIMENSIONS OF THIS DRAWING ARE TO CENTER UNLESS OTHERWISE SPECIFIED.

SCALE 20:1

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ISOLEAD TO18W

PL-048899; GND CAVITY

PACKAGE

RECOMMENDED FOR LEAD

6.1

Mirror Semiconductor